

19. (Amended) An electronic instrument provided with the semiconductor device as defined in claim 1. *in proper*

27. (Amended) The method of fabricating a semiconductor device as defined in claim 20, further comprising  
a step of forming a recognition hole in the substrate at a position differing from the holes, and forming a recognition pattern over the recognition hole on the side of a surface of the substrate including the interconnecting pattern.

29. (Amended) The method of fabricating a semiconductor device as defined in claim 20,  
wherein the conductive members are a plurality of layered bumps.

# REMARKS

Claims 1-32 are pending. By this Preliminary Amendment, claims 7, 10, 17-19, 27 and 29 are amended to eliminate multiple dependencies. Prompt and favorable consideration on the merits is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. 1.121(c)(1)(ii)).

Respectfully submitted,

*[Signature]*  
James A. Oliff  
Registration No. 27,075

Joel S. Armstrong  
Registration No. 36,430

IAO:JSA/zmc  
Attached: APPENDIX  
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**OLIFF & BERRIDGE, PLC**  
P.O. Box 19928  
Alexandria, Virginia 22320  
Telephone: (703) 836-6400

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